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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Philip A. Rochette PATENT APPLICATION
Serial No.: 10/817,619 Group Art Unit: 2814
Filed: April 1, 2004 Examiner: M. D. Pizarro-Crespo
For: METHOD AND APPARATUS TO ELIMINATE GALVANIC
CORROSION ON COPPER DOPED ALUMINUM BOND PADS
ON INTEGRATED CIRCUITS

Response to Restriction Requirement

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

In response to the Restriction Requirement in the Office action mailed 06/01/2005 from the Patent and Trademark Office regarding the above-identified patent application, Applicant elects to prosecute the invention of Group I, claims 1-5 and 14-18. Applicant withdraws the non-elected claims 6-13.

CERTIFICATE OF MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.

Signed: Merle P. Garcia
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Date: June 15, 2005

Respectfully submitted,

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